



# SOT1359-1

plastic thermal enhanced very thin profile land grid array  
package; no leads; 36 terminals;

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	HVLGA
<b>Package type industry code</b>	HVLGA36
<b>Package style descriptive code</b>	HLLGA (thermal enhanced low profile land grid array)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	27-1-2015

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	4.9	-	5	5.1	mm
E	package width	4.9	-	5	5.1	mm
A	seated height	0.62	-	0.72	0.82	mm
e	nominal pitch	-	-	0.4	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	36	-	



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## 2. Package outline

HVLGA36: plastic thermal enhanced very thin profile land grid array package; no leads; 36 terminals; SOT1359-1

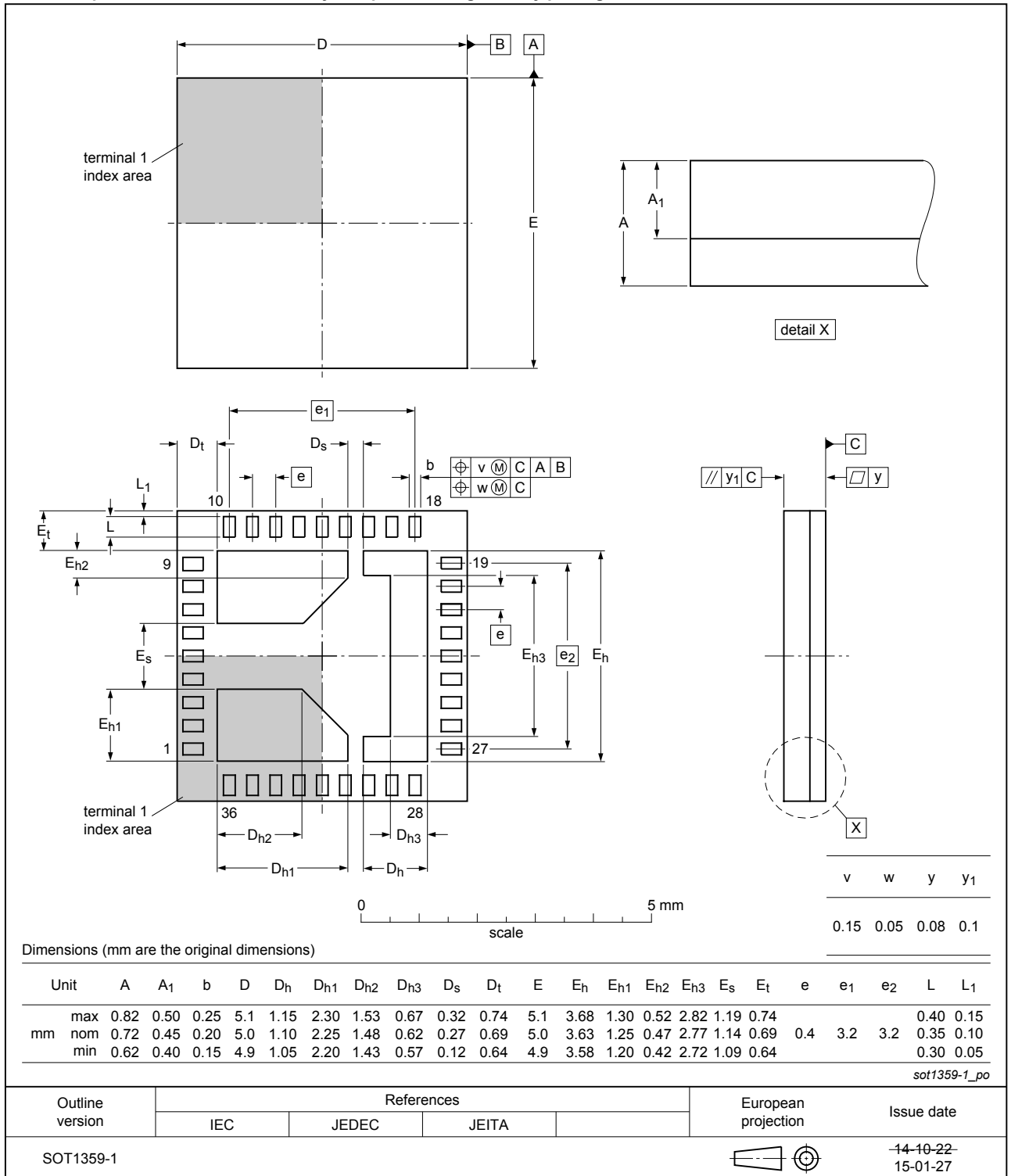


Fig. 1. Package outline HVLGA36 (SOT1359-1)

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### 3. Soldering

Footprint information for reflow soldering of SOT1359 package SOT1359-1

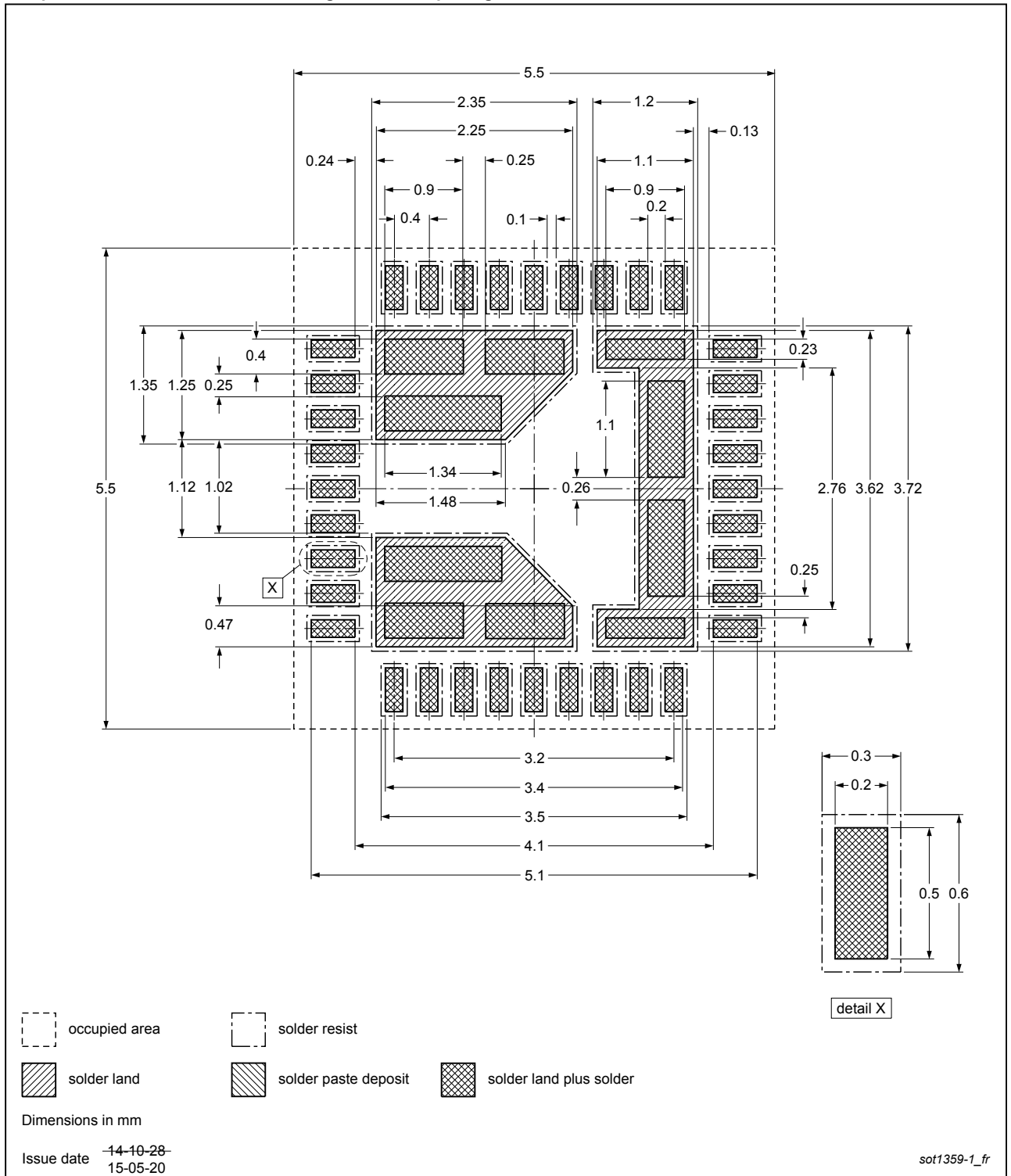


Fig. 2. Reflow soldering footprint for HVLGA36 (SOT1359-1)

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## 4. Legal information

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